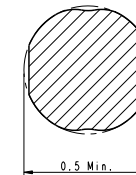
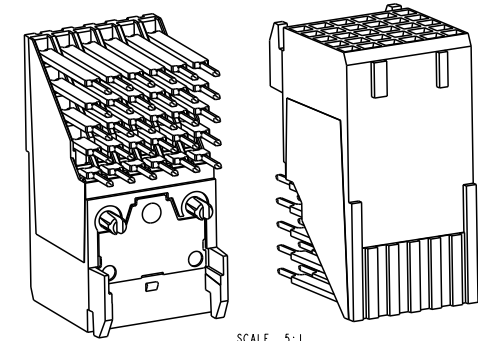
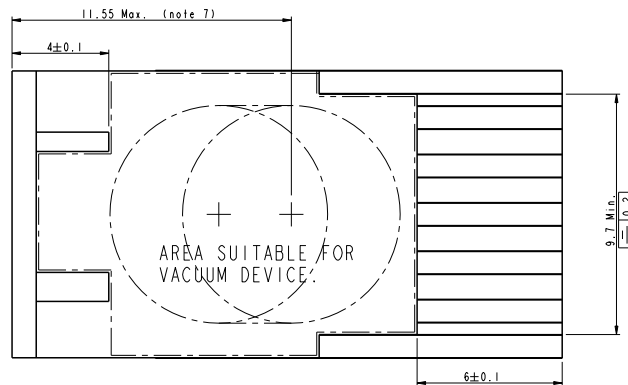


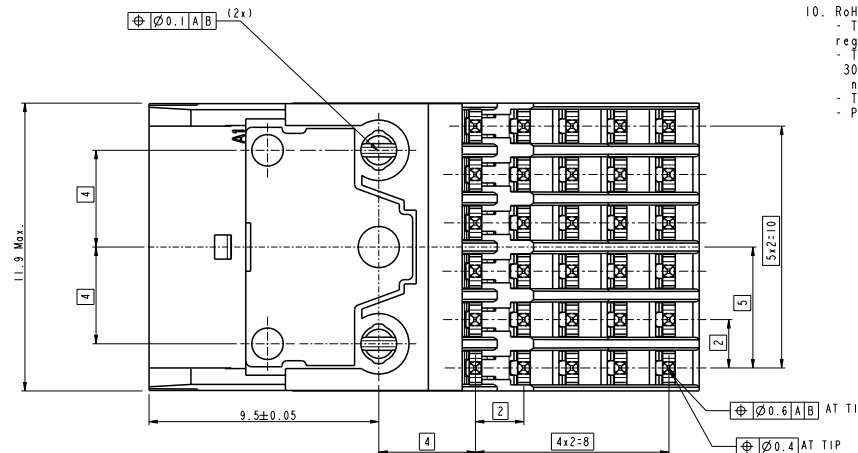
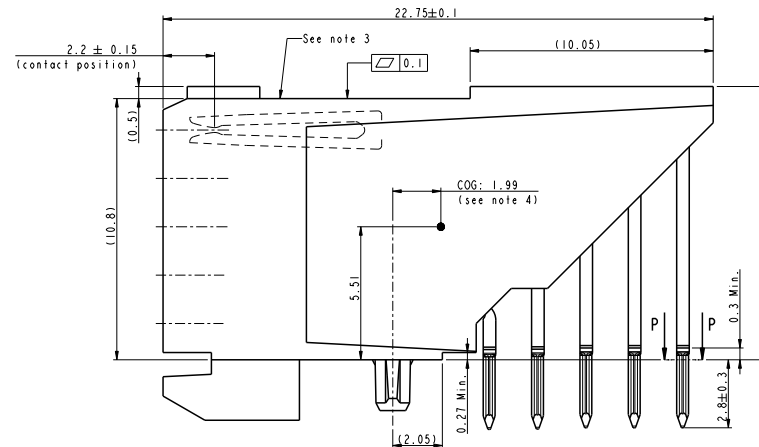
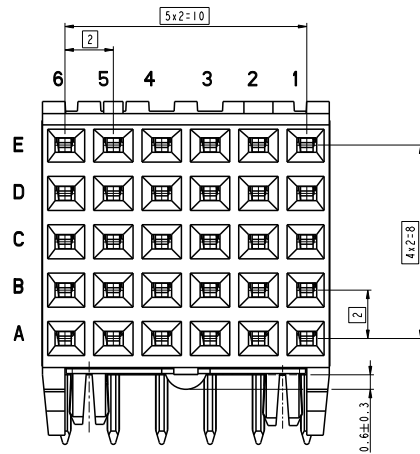
TIN LEAD PRODUCT NUMBER	ROW	6	5	4	3	2	1
52085-X01(LF)	E	X	X	X	X	X	X
performance level (see table)	D	X	X	X	X	X	X
loading pattern	C	X	X	X	X	X	X
Lead Free designation	B	X	X	X	X	X	X
	A	X	X	X	X	X	X

" " POSITION NOT LOADED
"X" POSITION LOADED

PRODUCT NUMBER	MATING PERFORMANCE LEVEL
52048-101(LF)	STANDARD P/N - TELCORDIA CO Compatible
52048-301(LF)	CUSTOMER SPECIFIC
52048-E01(LF)	CUSTOMER SPECIFIC



SECTION P-P
SCALE 100:1



NOTES:

- Housing material: Liquid Cristal Polymer 30% glass, flame retardant according to UL 94-V0. Contact material phosphor bronze.
- All solder surfaces are tin or tin-alloy plated.
- Product marking on indicated surface: part number and manufacturing code. It will not prevent picking up with a vacuum device.
- Center of gravity at indicated point. Mass of product 5.65 g.
- Maximum mounting force per connector 20N on bare board.
- This dimension shows maximum position of the centre of the vacuum nozzle. Recommended position is 9.5 mm in line with the pegs.
- The connector is tape-and-reel packed according to GS-14-626, which follows EIA-481B. Tape width 44 mm, cavity pitch 20 mm. The tape has recesses at the sides to allow use of gripper.
- Product specification according to GS-12-215.
- For pin-in-paste recommendation, see sheet 2 and application guide GS-20-024.

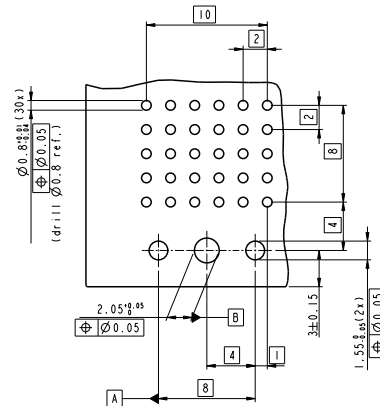
10. RoHS INFORMATION:

- The "LF" products meet European Union Directives and other country regulations as described in GS-22-008.
- The housing will withstand exposure to 260°C peak temperature for 30 seconds in a convection, infra-red or vapor reflow oven. See application notes/procedures if they are available.
- Termination plating spec: 1.27µm Ni mini, 2.5 to 7.5µm Sn (pure matte)
- Packaging spec: see GS-14-920

Material	Spec. ref.	surface	tolerance	projection	mm
Mat. code		ISO 406	ISO 406	ISO 1101	
Heat treat		ISO 1302	ISO 1101		
Plating/Finish					
Dr. IP Partner	2002/04/23				
Eng. P. Pollers	2002/04/23	Product family	Metral (17ml)	size A1	Scale 10:1
Chr. P. Pollers	2002/04/22	Model Name	52085 ECN	LS08-D110	Rev.
App. P. Pollers	2002/04/23	Model Revision	F REL Level	RELEASED	G
5x6 RA Assy					
Signal RCP PIP with NDF					
Prat. file	catalog no	metral	customer copy	sheet 1 of 2	

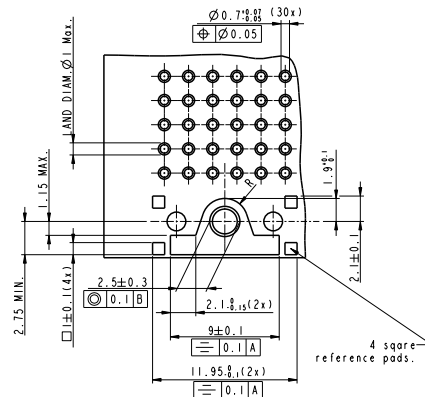
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PCB thickness 1.4 - 2.6 mm.

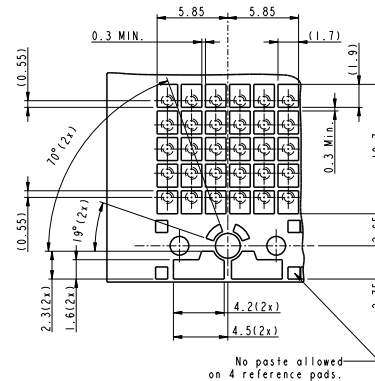


Technical drawing of a rectangular plate. The plate has a width of 12 and a height of 13.5 Max. The plate is filled with a grid of small circles, representing holes. A larger circular feature is located at the bottom center of the plate. The drawing includes dimension lines and a scale bar.

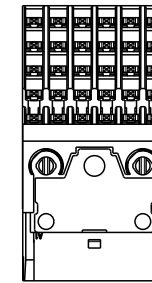
Plating thickness must be constant over the connector area. Copper layer 50 μm max. Solder mask should cover all surfaces under the paste that are not plated. There is no solder mask allowed on the reference pads.



Recommended stencil thickness 0.15 mm.
The solder content in the paste should be sufficient, typically 50% volume percentage.
The solder tail, PCB, stencil and application process determine the solder result. The squeegee process (angle, speed, pressure, material and number of cycles) must be optimized, so that sufficient solder is available.




The connector can be picked up with a mechanical gripper or a vacuum nozzle. Nozzle diameter 6 - 10 mm. Both metal nozzles or nozzles with seal or rubber can be used. Vacuum pressure 0.6 bar under local ambient pressure. Position of the nozzle on the connector as mentioned on sheet 1. The reference for placing the connector can be determined by video inspection of the connector bottomside. The recesses of the retention pegs are designed for video recognition (shown bold, see sketch below). The line through the center of the recesses is the reference for Y-direction and rotation; datum **B**. The line through the middle between the center of the recesses perpendicular to the first line is reference for X-direction; datum **A**.



The acceleration and the deceleration of the mounting head of the pick and place equipment should be restricted in such a way that the connector doesn't fall off or slides on the nozzle. An inferior accuracy of the placing equipment can reduce the success rate of mounting.

The last movement of the connector must be purely vertical and downwards. The board must be horizontal. The final mounting force must be controlled in such a way that the connector is seated flush to the board and remains there after releasing from the placing device. (Extra) PCB support can be required to meet this. The movement of the PCB-assembly before reflowing must be smooth so that all components remain seated flush on the board.

Material	-	Spec ref			
Mat code	-	surface	✓	tolerance	
Heat treat	-			ISO 406	
Plating/Finish	-	ISO 1302	✓	ISO 1101	
Dr. P. Positor	2002/04/23				Scale
Dr. P. Positor	2002/04/23	Product family	Metrol 11/m	size	A1
Chr. P. Positor	2002/04/22	Model Name	52085C	EN	LS08-0110
Appl. P. Positor	2002/04/23	Model Revision	F	REL Level	RELEASED
	51x6 RA Assy		no	52085C	
Signal RCP PIP with HDF		matrol	customer code	sheet 2 of 2	